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March 2015

FDD8447L 40V N-Channel PowerTrench® MOSFET **40V**, **50A**, **8.5m** Ω

Features

- Max $r_{DS(on)}$ = 8.5m Ω at V_{GS} = 10V, I_D = 14A
- Max $r_{DS(on)}$ = 11.0m Ω at V_{GS} = 4.5V, I_D = 11A
- Fast Switching
- RoHS Compliant



General Description

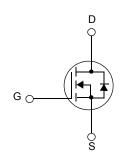
This N-Channel MOSFET has been produced using Fairchild Semiconductor's proprietary PowerTrench® technology to deliver low $r_{DS(on)}$ and optimized BV_{DSS} capability to offer superior performance benefit in the application.

Applications

- Inverter
- Power Supplies



(TO-252)



MOSFET Maximum Ratings T_C = 25°C unless otherwise noted

Symbol	Parameter	Ratings	Units	
V_{DS}	Drain to Source Voltage	40	V	
V_{GS}	Gate to Source Voltage	±20	V	
	Drain Current -Continuous (Package limited) T _C = 25°C	50		
	-Continuous (Silicon limited) T _C = 25°C	57		
ΙD	-Continuous T _A = 25°C (Note 1	a) 15.2	A	
	-Pulsed	100		
I _S	Max Pulse Diode Current	100	Α	
E _{AS}	Drain-Source Avalanche Energy (Note	3) 153	mJ	
	Power Dissipation T _C = 25°C	44		
P_D	$T_A = 25^{\circ}C$ (Note 1	a) 3.1	W	
	T _A = 25°C (Note 1	b) 1.3		
T _J , T _{STG}	Operating and Storage Junction Temperature Range	-55 to +150	°C	

Thermal Characteristics

$R_{\theta JC}$	Thermal Resistance, Junction to Case		2.8	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1a)	40	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1b)	96	

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDD8447L	FDD8447L	D-PAK(TO-252)	13"	16mm	2500 units

Electrical Characteristics T_J = 25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Chara	acteristics					
BV _{DSS}	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	40			V
$\frac{\Delta BV_{DSS}}{\Delta T_{J}}$	Breakdown Voltage Temperature Coefficient	I _D = 250μA, referenced to 25°C		35		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 32V$, $V_{GS} = 0V$			1	μА
I _{GSS}	Gate to Source Leakage Current	V _{GS} = ±20V, V _{GS} = 0V			±100	nA

On Characteristics (Note 2)

$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_D = 250 \mu A$	1.0	1.9	3.0	V	
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	I _D = 250μA, referenced to 25°C		-5		mV/°C	
r _{DS(on)}	Static Drain to Source On Resistance	V _{GS} = 10V, I _D = 14A		7.0	8.5		
		$V_{GS} = 4.5V, I_D = 11A$		8.5	11.0	mΩ	
		V _{GS} = 10V, I _D = 14A, T _J =125°C		10.4	14.0		
g _{FS}	Forward Transconductance	V _{DS} = 5V, I _D = 14A		58		S	

Dynamic Characteristics

C _{iss}	Input Capacitance	\\ - 20\\ \\ - 0\\	1970	pF
C _{oss}	Output Capacitance	V _{DS} = 20V, V _{GS} = 0V, f = 1MHz	250	pF
C _{rss}	Reverse Transfer Capacitance	1 - 1101112	150	pF
R_{g}	Gate Resistance	f = 1MHz	1.27	Ω

Switching Characteristics

t _{d(on)}	Turn-On Delay Time	$V_{DD} = 20V, I_{D} = 1A$ $V_{GS} = 10V, R_{GEN} = 6\Omega$	12	21	ns
t _r	Rise Time		12	21	ns
t _{d(off)}	Turn-Off Delay Time		38	61	ns
t _f	Fall Time		9	18	ns
$Q_{g(TOT)}$	Total Gate Charge, V _{GS} = 10V	V _{DD} = 20V, I _D = 14A V _{GS} = 10V	37	52	nC
$Q_{g(TOT)}$	Total Gate Charge, V _{GS} = 5V		20	28	nC
Q_{gs}	Gate to Source Gate Charge		6		nC
Q_{gd}	Gate to Drain "Miller" Charge		7		nC

Drain-Source Diode Characteristics

IS	Maximum Continuous Drain-Source Diode Forward Current (Note 1a)		ote 1a)		2.6	Α
V_{SD}	Source to Drain Diode Forward Voltage	$V_{GS} = 0V, I_S = 14A$ (No	te 2)	8.0	1.2	V
t _{rr}	Reverse Recovery Time	I _E = 14A, di/dt = 100A/μs		22		ns
Q _{rr}	Reverse Recovery Charge	1F = 14A, αι/αι = 100A/μS		11		nC

Notes

- 1: R_{0,IA} is the sum of the junction-to-case and case-to- ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. R_{0,IC} is guaranteed by design while R_{0,IA} is determined by the user's board design.
 - a. 40°C/W when mounted on a 1 in2 pad of 2 oz copper
 - b. 96°C/W when mounted on a minimum pad.
- 2: Pulse Test: Pulse Width < 300 μ s, Duty cycle < 2.0%.
- 3: Starting TJ = 25° C, L = 1mH, IAS = 17.5A, VDD = 40V, VGS = 10V.

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Typical Characteristics

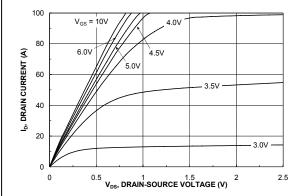


Figure 1. On-Region Characteristics

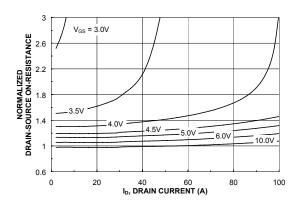


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage

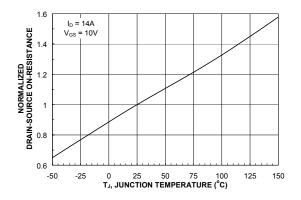


Figure 3. On-Resistance Variation with Temperature

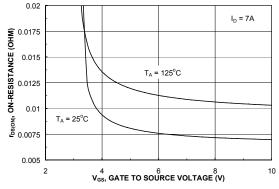


Figure 4. On-Resistance Variation with Gate-to-Source Voltage

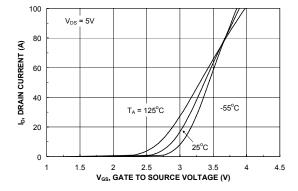


Figure 5. Transfer Characteristics

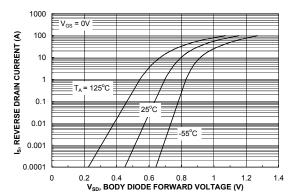


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature

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Typical Characteristics

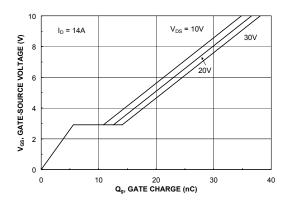


Figure 7. Gate Charge Characteristics

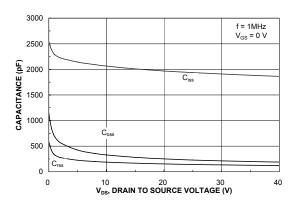


Figure 8. Capacitance Characteristics

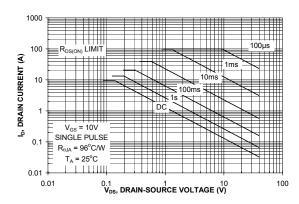


Figure 9. Maximum Safe Operating Area

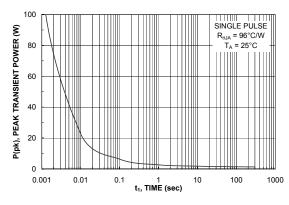


Figure 10. Single Pulse Maximum Power Dissipation

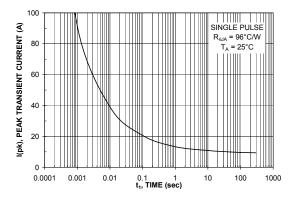


Figure 11. Single Pulse Maximum Peak Current

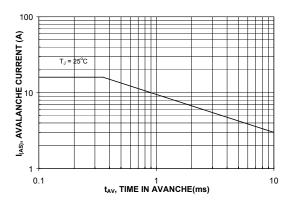


Figure 12. Unclamped Inductive Switching Capability

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Typical Characteristics

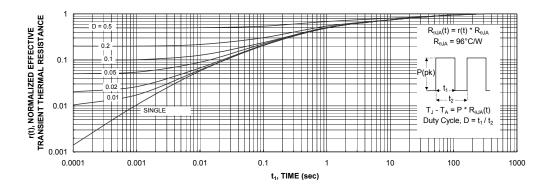
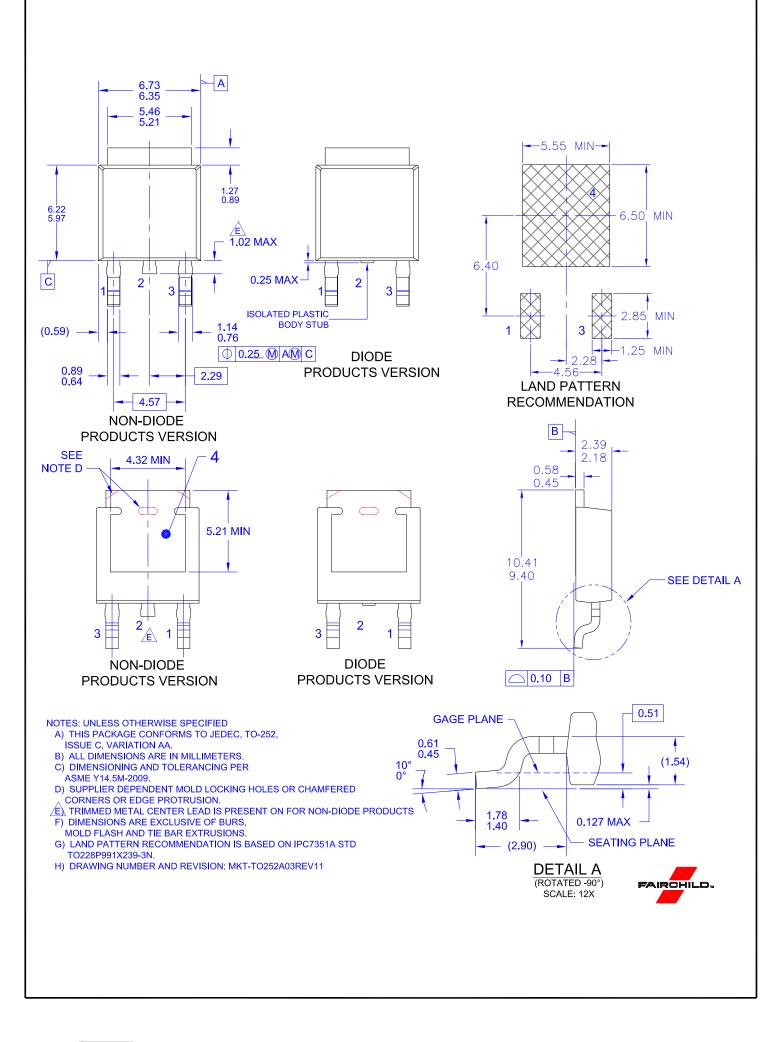


Figure 13. Transient Thermal Response Curve

Thermal characterization performed using the conditions described in Note 1b. Transient thermal response will change depending on the circuit board design.



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